L Number	Hits	Search Text	DB	Time stamp
1	619	239/432.ccls.	USPAT	2004/01/21 11:57
2	20	239/432.ccls. and (239/402.ccls. or 239/500.ccls. or 239/501.ccls. or 239/502.ccls.)	USPAT	2004/01/21 12:11
3	695	118/52.ccls.	USPAT	2004/01/21 12:24
4	235	118/612.ccls.	USPAT	2004/01/21 12:24
5	562	118/320.ccls.	USPAT	2004/01/21 12:25
6	112	118/402.ccls.	USPAT	2004/01/21 12:25
7	0	118/432.ccls.	USPAT	2004/01/21 12:25
8	619	239/432.ccls.	USPAT	2004/01/21 12:25
9	172	239/500.ccls.	USPAT	2004/01/21 12:26
10	32	239/501.ccls.	USPAT	2004/01/21 12:26
11	73	239/502.ccls.	USPAT	2004/01/21 12:27
12	126	239/402.ccls.	USPAT	2004/01/21 12:27

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L Number	Hits	Search Text	DB	Time stamp
1	619	239/432.ccls.	USPAT	2004/01/21 11:57
2	20	239/432.ccls. and (239/402.ccls. or 239/500.ccls. or 239/501.ccls. or 239/502.ccls.)	USPAT	2004/01/21 12:11
3	695	118/52.ccls.	USPAT	2004/01/21 12:24
4	235	118/612.ccls.	USPAT	2004/01/21 12:24
5	562	118/320.ccls.	USPAT	2004/01/21 12:25
6	112	118/402.ccls.	USPAT	2004/01/21 12:25
7	0	118/432.ccls.	USPAT	2004/01/21 12:25
8	619	239/432.ccls.	USPAT	2004/01/21 12:25
9	172	239/500.ccls.	USPAT	2004/01/21 12:26
10	32	239/501.ccls.	USPAT	2004/01/21 12:26
11	73	239/502.ccls.	USPAT	2004/01/21 12:27
12	126	239/402.ccls.	USPAT	2004/01/21 12:28
13	14	118/52.ccls. and (atomized or atomizing or atomizer)	USPAT	2004/01/21 12:29
14	3	wafer and semiconductor and (atomized or atomizing or atomizer) and coating	JPO; DERWENT	2004/01/21 12:29